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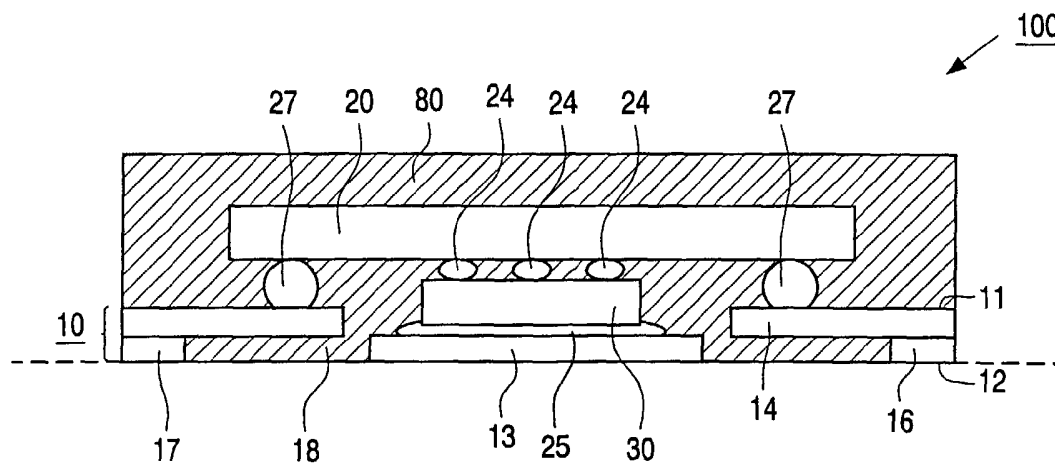
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Declaration under Rule 4.17:

— as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii)) for the following designations AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG,

[Continued on next page]

(54) Title: ELECTRONIC DEVICE AND METHOD OF MANUFACTURING SAME



(57) Abstract: The electronic device (100) is a chip-on-chip construction on a lead frame (10) comprising a heat sink (13) in an encapsulation (80). The first chip (20) and the second chip (30) are mutually connected by first conductive interconnections (24) and the first chip (20) is connected to the lead frame (10) by second conductive interconnections (27) which preferably have a lower reflow temperature than the first conductive interconnections (24). By heating the device (100) the adhesive layer (25) will first shrink, causing a stress, which will be relaxed by reflowing the second conductive interconnections (27).

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B. FIELDS SEARCHED
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Electronic data base consulted during the international search (name of data base and, where practical, search terms used)
PAJ, EPO-Internal, WPI Data

C. DOCUMENTS CONSIDERED TO BE RELEVANT

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A	US 2002/093087 A1 (PAEK JONG SIK) 18 July 2002 (2002-07-18) the whole document ---	1,8
A	US 2002/105789 A1 (CHAN LIEN-CHIH ET AL) 8 August 2002 (2002-08-08) the whole document ---	1,8
A	PATENT ABSTRACTS OF JAPAN vol. 1996, no. 09, 30 September 1996 (1996-09-30) -& JP 08 125112 A (HITACHI LTD; HITACHI VLSI ENG CORP), 17 May 1996 (1996-05-17) the whole document --- -/--	1,8

Further documents are listed in the continuation of box C. Patent family members are listed in annex.

° Special categories of cited documents :

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Date of the actual completion of the international search <p style="text-align: center;">7 June 2004</p>	Date of mailing of the international search report <p style="text-align: center;">21/06/2004</p>
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Name and mailing address of the ISA European Patent Office, P.B. 5818 Patentlaan 2 NL - 2280 HV Rijswijk Tel. (+31-70) 340-2040, Tx. 31 651 epo nl, Fax: (+31-70) 340-3016	Authorized officer <p style="text-align: center;">Zeisler, P</p>
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